

LX08M

● FEATURES

- * Halogen-free type
- * Glass passivated chip junctions
- * Compliance to RoHS product
- * Leadless chip form, no lead damage
- * Low power loss, High efficiency
- * High current capability
- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0

● APPLICATION

- * Lighting
- * AC/DC Power Supply
- * Communication Equipment

● MECHANICAL DATA

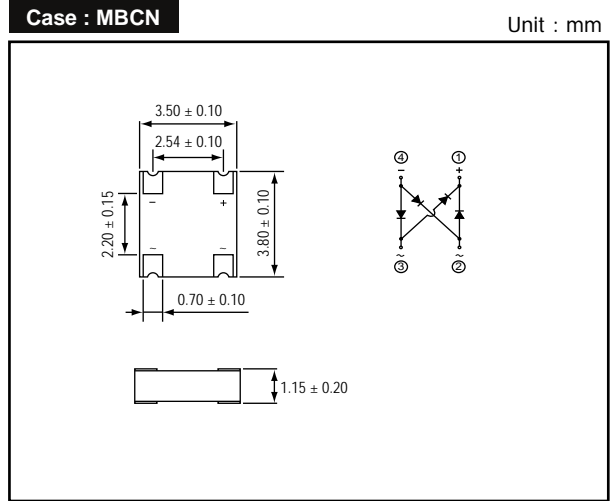
Case : Packed with FRP substrate and epoxy underfilled

Terminals : Pure Tin plated (Lead-Free),
solderable per MIL-STD-750, Method 2026.

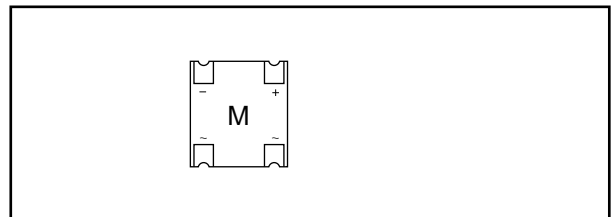
● PACKING

- * 5,000 pieces per 13" (330mm ± 2mm) reel
- * 2 reels per box
- * 5 boxes per carton

● OUTLINE DIMENSIONS



● MARKING



Absolute Maximum Ratings (Ta = 25 °C)

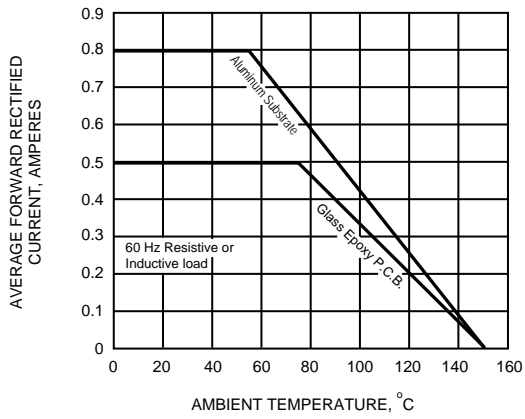
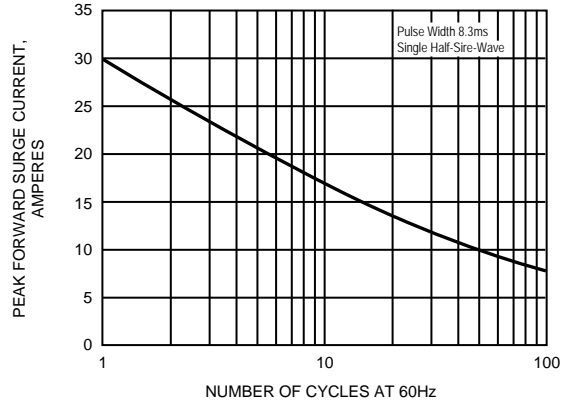
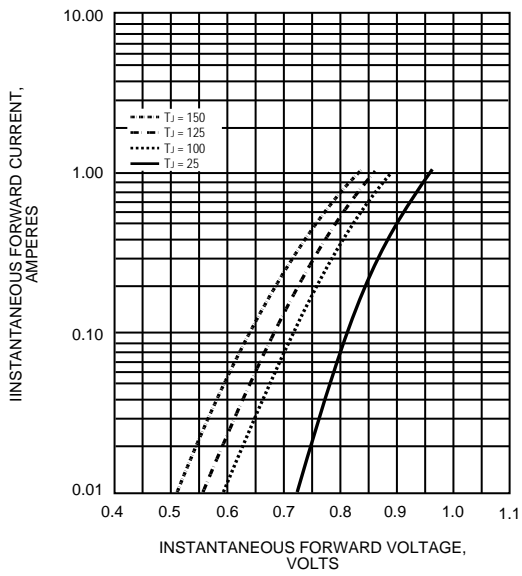
ITEM	Symbol	Conditions	Rating	Unit
Repetitive peak reverse voltage	V _{RRM}		1000	V
Average forward output rectified current (Fig.1)	I _{F(AV)}	on glass-epoxy P.C.B. (Note 1) on aluminum substrate (Note 2)	0.5 0.8	A
Peak forward surge current	I _{FSM}	8.3ms single half sine-wave	30	A
Operating junction and storage temperature Range	T _J , T _{STG}		-55 to +150	°C

Electrical characteristics (Ta = 25 °C)

ITEM	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward voltage	V _F	I _F = 0.4A	-	0.90	1.0	V
Repetitive peak reverse current	I _{RRM}	V _R = Max. V _{RRM} Ta = 25 °C Ta = 125 °C	- -	0.08 -	5 100	µA
Current squared time	I ² t	t < 8.3ms, Ta = 25 °C	-	3.74	-	A ² s
Typical thermal resistance per leg	R _{th(JA)}	Junction to ambient (Note 1)	-	130	-	°C/W
	R _{th(JC)}	Junction to case (Note 1)	-	40	-	°C/W

NOTES: (1) On glass epoxy P.C.B. mounted on 0.05" x 0.05" (1.3 x 1.3 mm) solder pads.

(2) On aluminum substrate P.C.B. with an area of 0.8 x 0.8" (20 x 20 mm) mounted on 0.05" x 0.05" (1.3 x 13. mm) solder pads.

FIG.1 - FORWARD CURRENT DERATING CURVE

FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

FIG.4 - TYPICAL REVERSE CHARACTERISTICS
